



# Final Product/Process Change Notification

Document #:FPCN24531X

Issue Date:01 Feb 2022

<b>Title of Change:</b>	Qualification of Alternate Mold Compound (G770HCD) for SOIC-14 package in HANA due to Show Denko supply shortage for CEL8240HF (Pellet size : 14x5.0g).
<b>Proposed First Ship date:</b>	08 May 2022 or earlier if approved by customer
<b>Contact Information:</b>	Contact your local onsemi Sales Office or <a href="mailto:Seok-Ho.Choi@onsemi.com">Seok-Ho.Choi@onsemi.com</a>
<b>PCN Samples Contact:</b>	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
<b>Additional Reliability Data:</b>	Contact your local onsemi Sales Office or <a href="mailto:Marco.kang@onsemi.com">Marco.kang@onsemi.com</a>
<b>Type of Notification:</b>	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <a href="mailto:PCN.Support@onsemi.com">PCN.Support@onsemi.com</a>
<b>Marking of Parts/ Traceability of Change:</b>	Change will be identifiable by lot# that will be using the alternate new mold compound.
<b>Change Category:</b>	Assembly Change
<b>Change Sub-Category(s):</b>	Material Change

**Sites Affected:**

**onsemi Sites**

None

**External Foundry/Subcon Sites**

HANA Semiconductor, Thailand

**Description and Purpose:**

onsemi would like to notify its customers of the qualification of alternate mold compound, G770HCD, at its subcon, HANA Thailand, for its SOIC package. This qualification is required due to notification from our current supplier, Showa Denko of an impending supply shortage for mold compound type CEL8240HF. This will allow package flexibility with regards to assembly production support depending on the mold compound availability and help to prevent any kind of supply disruption. Our notification from Showa Denko had a short window and we ask that customers immediately qualify the change.

	Before Change Description	After Change Description
Mold Compound	CEL8240(14x5)	CEL8240(14x5) & G770HCD(14x5)



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## Reliability Data Summary:

QV DEVICE NAME : FAN7384MX

RMS : O79397

PACKAGE : SOIC-14

Test	Specification	Condition	Interval	Result
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0/240
PC	J-STD-020A JESD22-A113	MSL 1 @ 245/260°C		
TC	JESD22-A104	Ta= -65°C to +150°C	1000 cycles	0/240
THB	JESD22-A101	Temp = 85C, RH=85%, bias = 100% of rated V or 100V max	1008hrs	0/240
UHASt	JESD22-A118	Temp=130°C, 85% RH	96 hrs	0/240
PD	JESD22-B100B			

## Electrical Characteristics Summary:

Electrical characteristics are not impacted.

## List of Affected Parts:

**Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Part Number	Qualification Vehicle
FAN7382M1X	N/A
FAN7384MX	N/A
FAN7390AMX1	N/A
FAN7390M1X	N/A
FAN7391MX	N/A
FAN73933MX	N/A
FAN7393AMX	N/A